Silicon N-Channel Power MOS FET Module

HITACHI

Application

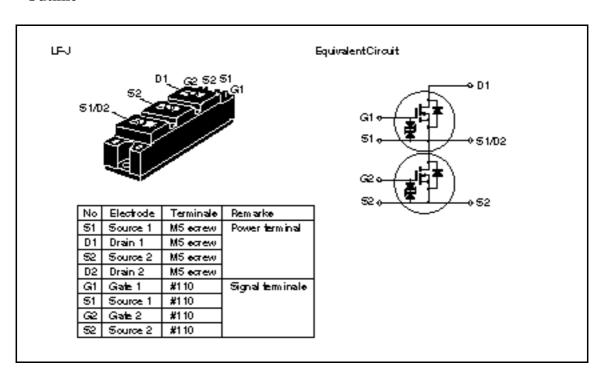
High Speed Power Switching

Features

- Equipped with Power MOS FET
- Low on-resistance
- · High speed switching
- · Low drive current
- Wide area of safe operation
- Inherent parallel diode between source and drain
- · Isolated base from Terminal
- Suitable for motor driver, switching regulator and etc.



Outline



Absolute Maximum Ratings (Ta = 25°C) (Per FET chip)

Item	Symbol	Rating	Unit
Drain source voltage	$V_{(BR)DSS}$	500	V
Gate source voltage	$V_{(BR)GSS}$	±30	V
Drain current	I _D	50	А
Drain peak current	I D(peak)	120	А
Body to drain diode reverse drain current	I _{DR}	50	А
Body to drain diode reverse peak current	I DR(peak)	120	А
Channel dissipation	Pch*1	250	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-45 to +125	°C
Insulation dielectric	Viso*2	2000	Vrms

Notes: 1. Value at Ta = 25°C

2. Base to terminals AC minute

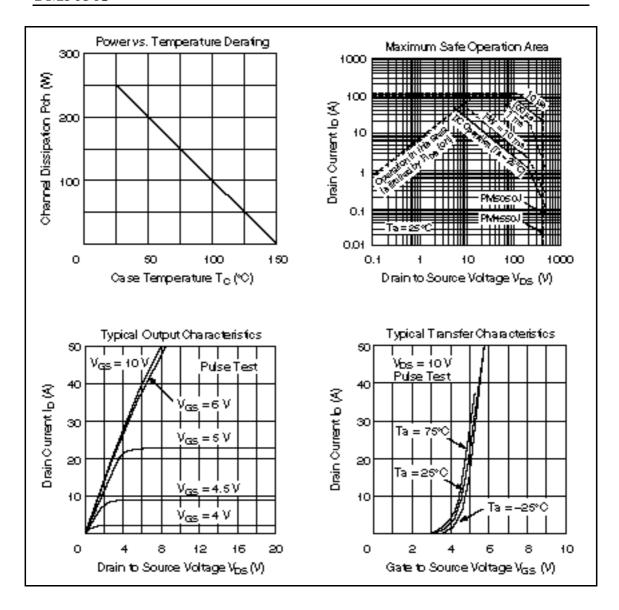
Electrical Characteristics (Ta = 25°C) (Per FET chip)

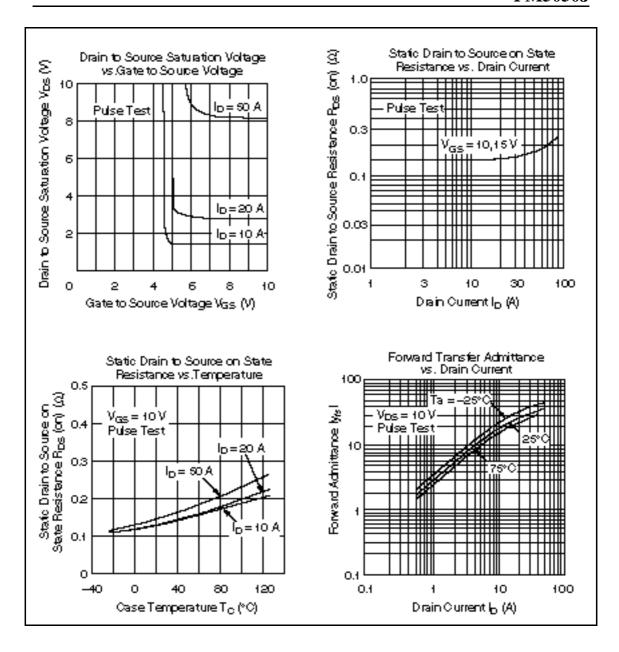
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	500	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate to source leak current	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0 \ V$
Drain leak current	I _{DSS}	_	_	500	μA	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$
Gate to source threshold voltage	$V_{\text{GS(th)}}$	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Drain to source saturation voltage	$V_{\mathrm{DS(on)}}$	_	3.5	4.5	V	$I_D = 25 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
Static drain to source on state resistance	$R_{\mathrm{DS(on)}}$	_	0.14	0.18		$I_D = 25 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
Forward transfer admittance	y _{fs}	_	30	_	S	$I_D = 25 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	6600	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}$
Output capacitance	Coss	_	1550	_	_	f = 1 MHz
Reverse transfer capacitance	Crss	_	250	_		
Turn-on delay time	$t_{d(on)}$	_	45	_	ns	$I_D = 25 \text{ A}, V_{GS} = 10 \text{ V}$
Rise time	t _r	_	270	_	_	Rg = 50
Turn-off delay time	$t_{d(off)}$	_	250	_		$R_{L} = 1.2$
Fall time	t _f	_	140	_	_	
Body to drain diode forward voltage	V_{DF}	_	1.6	_	V	$I_F = 50 \text{ A}, V_{GS} = 0 \text{ V}$
Body to drain diode reverse recovery time	t _{rr}	_	130	_	ns	$I_F = 50 \text{ A}, V_{GS} = 0 \text{ V}$ di/dt = 100 A/ μ s

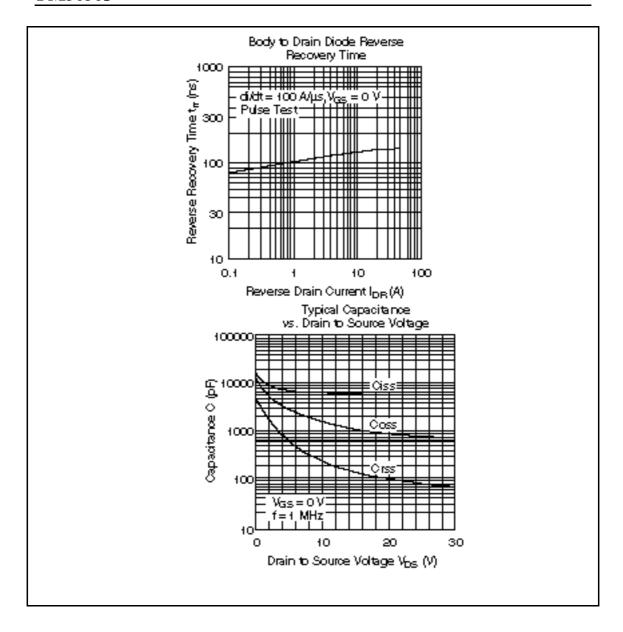
Note: 1. Pulse Test

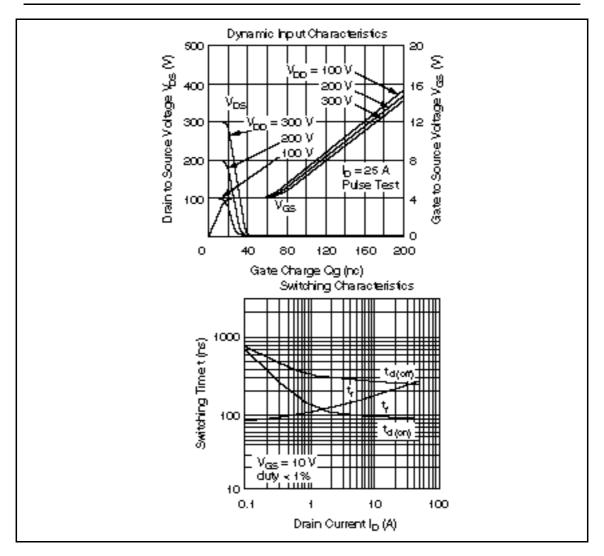
Mechanical Characteristics

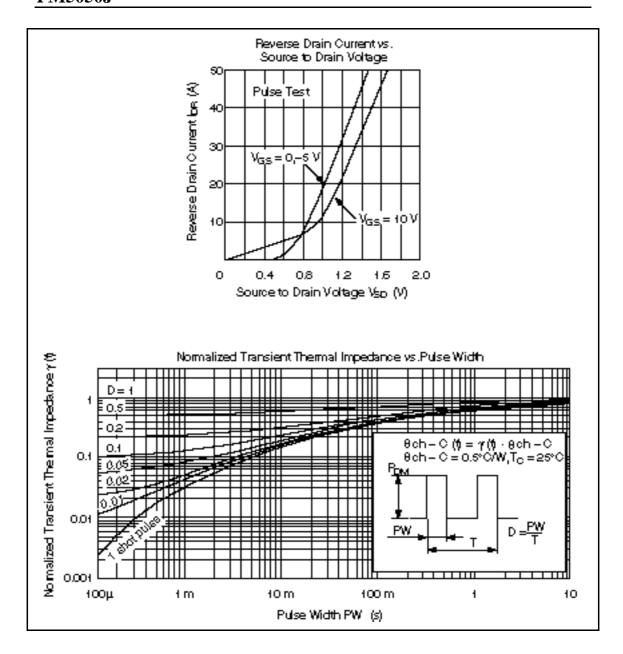
Item	Symbol	Condition	Rating	Unit
Fixing strength	_	Mounting into main-terminal with M4 screw	1.45 to 1.95	N-m
	_	Mounting into heat sink with M5 screw	1.95 to 2.9	N-m
Weight	_	Typical value	200	g

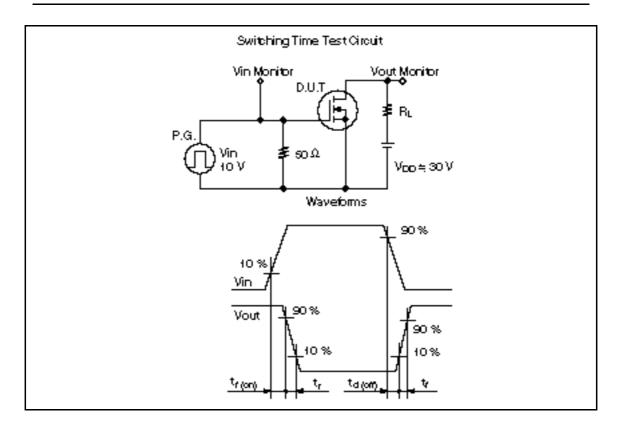






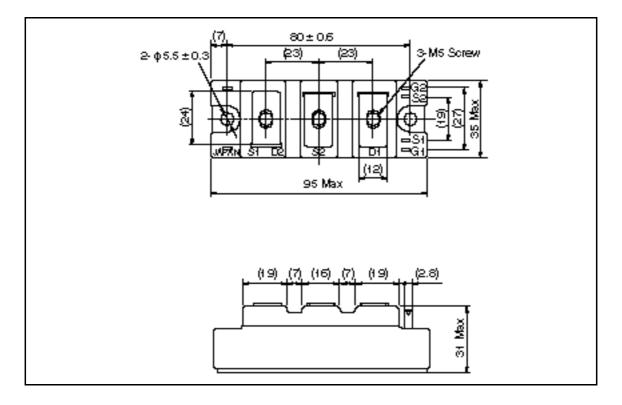






Package Dimensions

Unit: mm



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HITACHI

Histochi, Ltd. Semiconductor & IC Div. Neppon Bidg, 2-6-2, Ohte-medii, Chiyode-ku, Tokyo 100, Japan Tet Tokyo (03, 3270-2111) Fex: (03, 3270-5109)

For Author in formellon write to:

His chi Americe, Ltd.
Semiconductor & IC Div.
2000 Sierre Point Perlavey
Brisbane, CA. 94005-1835
U.S.A.
Tet 415-589-8300
Fex: 415-583-4207

Bedronic Components Group Cartinertal Burope Danacher Straße 3 D-85622 Feldkirchen München Tet 089-9 94 80-0 Fex: 089-9 29 30 00

Hitechi Burope GmbH

Hitachi Burope Ltd.
Bedronic Componenta Dw.
Northern Burope Headquartera
Whitebrook Park
Lower Cook ham Road
Heidenhead
Barkshire SL68YA
Urited Kingdom
Tet 0628-858000
Fex: 0628-778322

Hitachi Asia Pta, Ltd 45 Collyer Quay \$20-00 Hitachi Tower Snappore 0404 Tet 535-2400 Fex: 535-4533

Hischi Asia (Hong Kong) Ltd. Unit 705, North Towar, World Finance Centre, Harbour City, Centon Road Taim She Taul, Kowloon Hong Kong Tet 27:350218 Fax: 27:30607 f